## PRODUCT FEATURES

- **Complete System Solution for interfacing SmartMedia™ (SM) or xD Picture Card™ (xD), Memory Stick™ (MS), High Speed Memory Stick (HSMS), Memory Stick PRO (MSPRO), MS Duo™, Secure Digital (SD), Mini-Secure Digital (Mini-SD), TransFlash (SD), MultiMediaCard™ (MMC), Reduced Size MultiMediaCard (RS-MMC), NAND Flash, Compact Flash™ (CF) and CF Ultra™ I & II, and CF form-factor ATA hard drives to USB 2.0 bus**
  - Supports USB Bulk Only Mass Storage Compliant Bootable BIOS
  - Support for simultaneous operation of all above devices. (only one at a time of each of the following groups supported: CF or ATA drive, SM or XD or NAND, SD or MMC)
- **On-Chip 4-Bit High Speed Memory Stick and MS PRO Hardware Circuity**
- **On-Chip firmware reads and writes High Speed Memory Stick and MS PRO**
- **1-bit ECC correction performed in hardware for maximum efficiency**
- **Hardware support for SD Security Command Extensions**
- **On-chip power FETs for supplying flash media card power with minimum board components**
- **USB Bus Power Certified**
- **3.3 Volt I/O with 5V input tolerance on VBUS/GPIO3**
- **Complete USB Specification 2.0 Compatibility for Bus Powered Operation**
  - Includes USB 2.0 Transceiver
  - A Bi-directional Control and a Bi-directional Bulk Endpoint are provided.
- **8051 8 bit microprocessor**
  - Provides low speed control functions
  - 30 MHz execution speed at 4 cycles per instruction average
  - 12K Bytes of internal SRAM for general purpose scratchpad
  - 768 Bytes of internal SRAM for general purpose scratchpad or program execution while re-flashing external ROM
- **Double Buffered Bulk Endpoint**
  - Bi-directional 512 Byte Buffer for Bulk Endpoint
  - 64 Byte RX Control Endpoint Buffer
  - 64 Byte TX Control Endpoint Buffer

- **Internal or External Program Memory Interface**
  - 64K Byte Internal Code Space or Optional 64K Byte External Code Space using Flash, SRAM or EPROM memory.
- **On Board 24Mhz Crystal Driver Circuit**
- **Can be clocked by 48MHz external source**
- **On-Chip 1.8V Regulator for Low Power Core Operation**
- **Internal PLL for 480Mhz USB 2.0 Sampling, Configurable MCU clock**
- **Supports firmware upgrade via USB bus if “boot block” Flash program memory is used**
- **15 GPIOs for special function use: LED indicators, button inputs, power control to memory devices, etc.**
  - Inputs capable of generating interrupts with either edge sensitivity
  - Attribute bit controlled features:
  - Activity LED polarity/operation/blink rate
  - Full or Partial Card compliance checking
  - Bus or Self Powered
  - LUN configuration and assignment
  - Write Protect Polarity
  - SmartDetach™ Detach from USB when no Card Inserted for Notebook apps
  - Cover Switch operation for xD compliance
  - Inquiry Command operation
  - SD Write Protect operation
  - Older CF card support
  - Force USB 1.1 reporting
  - Internal or External Power FET operation
- **Compatible with Microsoft WinXP, WinME, Win2K SP3, Apple OS10, Softconnex, and Linux Multi-LUN Mass Storage Class Drivers**
- **Win2K, Win98/98SE and Apple OS8.6 and OS9 Multi-LUN Mass Storage Class Drivers available from SMSC**
- **128 Pin VTQFP Lead-free RoHS Compliant Package**
  - (1.0mm height, 14mm x14mm footprint)

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1.xD Picture Card not applicable to USB2227
ORDER NUMBER(S):
USB2227/USB2228-NU-XX FOR 128 PIN, VTQFP LEAD-FREE ROHS COMPLIANT PACKAGE
General Description

The USB2227/USB2228 is a USB 2.0 Bulk Only Mass Storage Class Peripheral Controller intended for supporting CompactFlash (CF and CF Ultra I/II) in True IDE Mode only, SmartMedia (SM) and XD cards, Memory Stick (MS), Memory Stick DUO (MSDUO) and Memory Stick Pro (MSPRO), Secure Digital (SD), and MultiMediaCard (MMC) flash memory devices. It provides a single chip solution for the most popular flash memory cards in the market.

The device consists of a USB 2.0 PHY and SIE, buffers, Fast 8051 microprocessor with expanded scratchpad, and program SRAM, and CF, MS, SM and SD controllers. The SD controller supports both SD and MMC devices. SM controller supports both SM and xD cards.

Provisions for external Flash Memory up to 64K bytes for program storage is provided.

12K bytes of scratchpad SRAM and 768 Bytes of program SRAM are also provided.

Fifteen GPIO pins are provided for indicators, external serial EEPROM for OEM id and system configuration information, and other special functions.

Internal power FETs are provided to directly supply power to the xD/SM, MMC/SD and MS/MSPro cards.

The internal ROM program is capable of implementing any combination of single or multi-LUN CF/SD/MMC/SM/MS reader functions with individual card power control and activity indication. SMSC also provides licenses** for Win98 and Win2K drivers and setup utilities. Note: Please check with SMSC for precise features and capabilities for the current ROM code release.

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Figure 1 USB2227/USB2228 Block Diagram
### Package Outlines

![USB2227/USB2228 128-Pin VTQFP Package Outline](image)

#### Table 1 USB2227/USB2228 128-Pin VTQFP Package Parameters

<table>
<thead>
<tr>
<th>MIN</th>
<th>NOMINAL</th>
<th>MAX</th>
<th>REMARKS</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>~</td>
<td>1.20</td>
<td>Overall Package Height</td>
</tr>
<tr>
<td>A1</td>
<td>0.05</td>
<td>0.15</td>
<td>Standoff</td>
</tr>
<tr>
<td>A2</td>
<td>0.95</td>
<td>1.05</td>
<td>Body Thickness</td>
</tr>
<tr>
<td>D</td>
<td>15.80</td>
<td>16.20</td>
<td>X Span</td>
</tr>
<tr>
<td>D1</td>
<td>13.80</td>
<td>14.20</td>
<td>X body Size</td>
</tr>
<tr>
<td>E</td>
<td>15.80</td>
<td>16.20</td>
<td>Y Span</td>
</tr>
<tr>
<td>E1</td>
<td>13.80</td>
<td>14.20</td>
<td>Y body Size</td>
</tr>
<tr>
<td>H</td>
<td>0.09</td>
<td>0.20</td>
<td>Lead Frame Thickness</td>
</tr>
<tr>
<td>L</td>
<td>0.45</td>
<td>0.75</td>
<td>Lead Foot Length</td>
</tr>
<tr>
<td>L1</td>
<td>1.00</td>
<td>~</td>
<td>Lead Length</td>
</tr>
<tr>
<td>e</td>
<td>0.40</td>
<td></td>
<td>Basic Lead Pitch</td>
</tr>
<tr>
<td>q</td>
<td>0°</td>
<td>~</td>
<td>Lead Foot Angle</td>
</tr>
<tr>
<td>W</td>
<td>0.13</td>
<td>0.23</td>
<td>Lead Width</td>
</tr>
<tr>
<td>R1</td>
<td>0.08</td>
<td>~</td>
<td>Lead Shoulder Radius</td>
</tr>
<tr>
<td>R2</td>
<td>0.08</td>
<td>0.20</td>
<td>Lead Foot Radius</td>
</tr>
<tr>
<td>ccc</td>
<td>~</td>
<td>0.08</td>
<td>Coplanarity</td>
</tr>
</tbody>
</table>

#### Notes:
1. Controlling Unit: millimeter.
2. Tolerance on the true position of the leads is ± 0.035 mm maximum.
   - Package body dimensions D1 and E1 do not include the mold protrusion.
3. Maximum mold protrusion is 0.25 mm.
4. Dimension for foot length L measured at the gauge plane 0.25 mm above the seating plane.
5. Details of pin 1 identifier are optional but must be located within the zone indicated.